


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMG/18/10669	
1.3 Title of PCN	Qualification of ASE WeiHai for D2PAK package (GPA Division)	
1.4 Product Category	See attached product list	
1.5 Issue date	2018-02-14	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	MARCELI SMIALKOWSKI
2.1.2 Phone	+44 1628896277
2.1.3 Email	marceli.smialkowski@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Marcello SAN BIAGIO
2.1.3 Quality Manager	Jean-Marc BUGNARD

**3. Change**

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	- ST Shenzhen - ASE WeiHai

**4. Description of change**

	Old	New
4.1 Description	Assembly, Test and Finishing : - ST Shenzhen	Assembly, Test and Finishing : - ST Shenzhen - ASE WeiHai
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

**5. Reason / motivation for change**

5.1 Motivation	The introduction of ASE WeiHai for both Assembly and Test & Finishing activities will allow us to rationalize our manufacturing assets and improve our manufacturing process for higher volume production in order to provide a better support to our customers.
5.2 Customer Benefit	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

6.1 Description	New finished good code
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**7. Timing / schedule**

7.1 Date of qualification results	2018-01-12
7.2 Intended start of delivery	2018-05-19
7.3 Qualification sample available?	Upon Request

**8. Qualification / Validation**

8.1 Description	10669 399-W-17-Qualification Subcon D2pak package Cu wire in Ase Weihai.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-02-14

9. Attachments (additional documentations)
10669 Public product.pdf 10669 399-W-17-Qualification Subcon D2pak package Cu wire in Ase Weihai.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
L7805ABD2T-TR	L7805ABD2T-TR	
L7805CD2T-TR	L7805CD2T-TR	
LM317D2T-TR	LM317D2T-TR	

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